

Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

NO.	Parameter	SPC
1	Frequency range(MHz)	2500~3500
2	Insertion Loss (dB)@25°C	≤2.0
3	VSWR	≤1.6
4	In Band Flatness	≤1.5
5	Attenuation(dBc)	≥60 @0~1200MHz
		≥50 @1500~1800MHz
6	In/Output Impedance (Ω)	50
7	Power(W)	5W

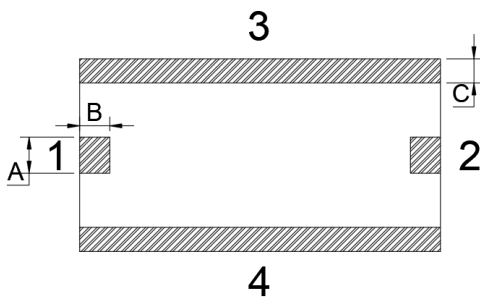
Operating & Storage Condition (Component)

Operation Temperature Range: -40°C ~ +85°C
 Storage Temperature Range: -40°C~ +85°C

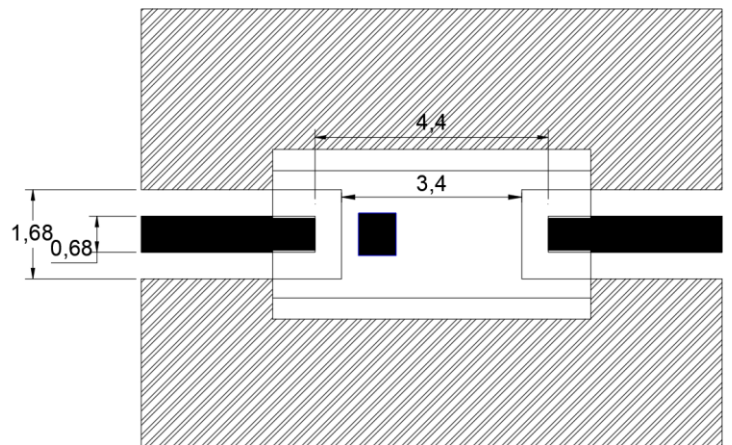
Storage Condition before Soldering (Included packaging material)

Storage Temperature Range: +5 ~ +40 °C
 Humidity: 30 to 70% relative humidity

Construction

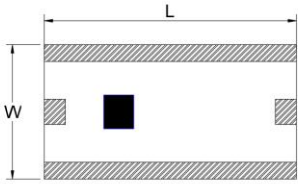

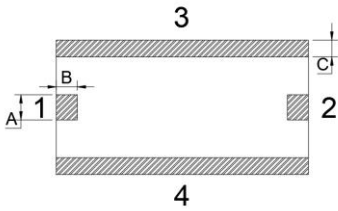


Mounting Considerations

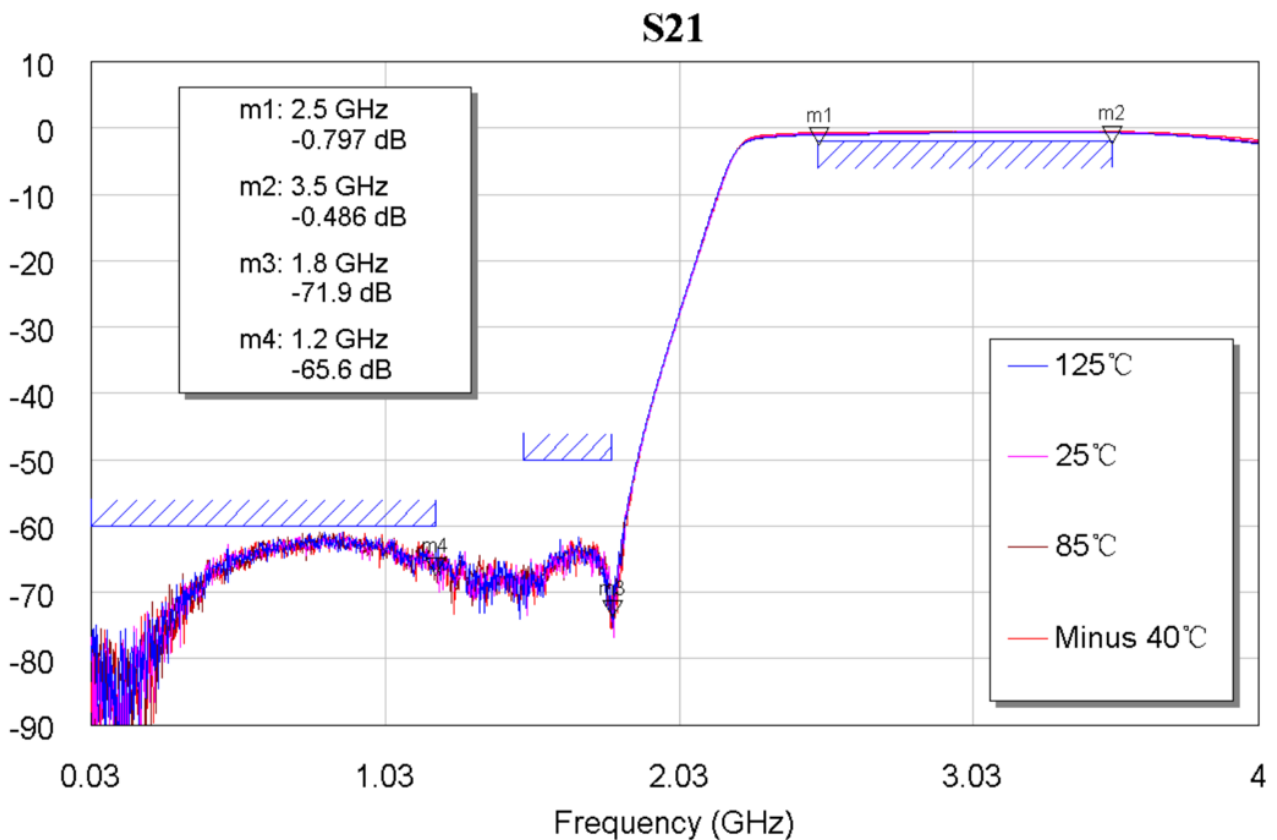


PIN	Connection	PIN	Connection
1	input Port	2	output Port
3	GND	4	GND

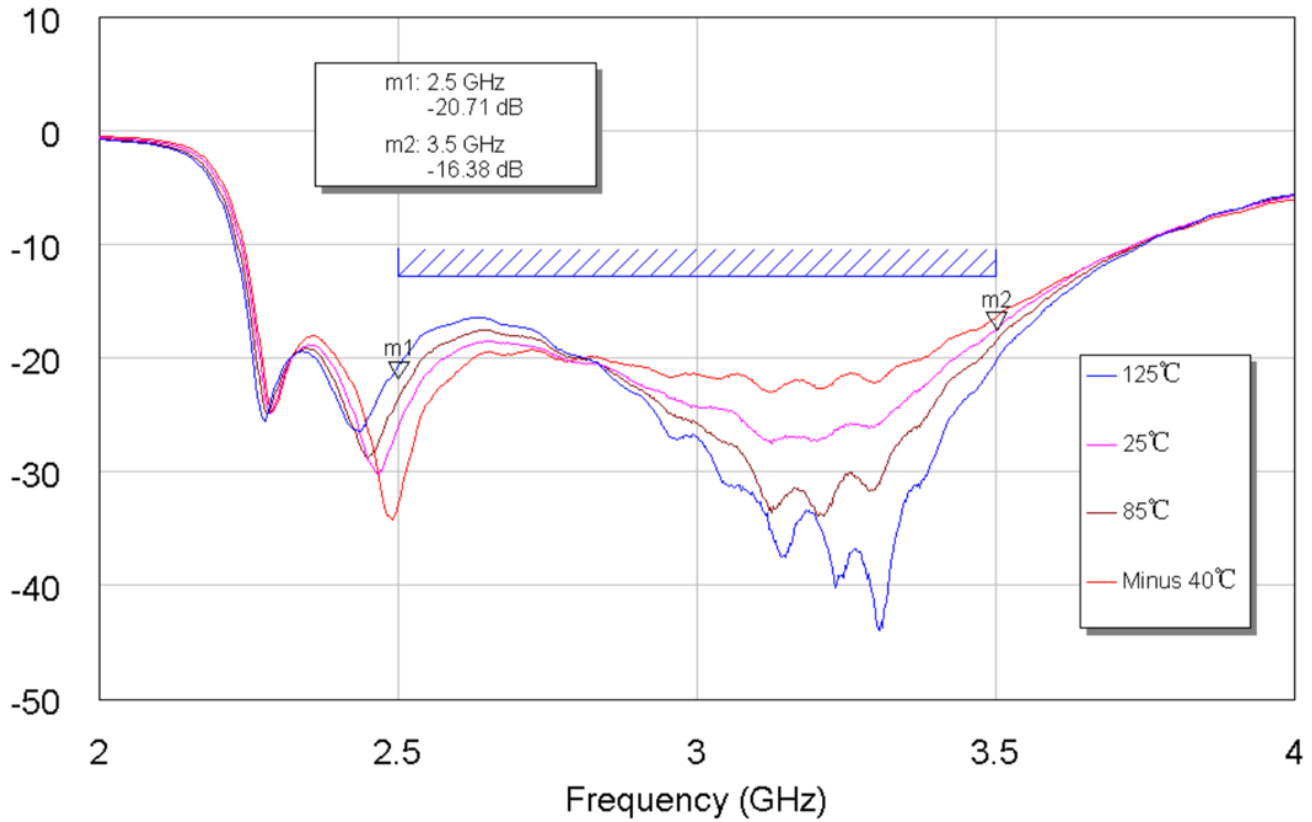
Dimensions

Figure	Symbol	Dimension (mm)
	L	6.00 ± 0.20
	W	3.20 ± 0.20
	T	1.50 ± 0.20
	A	0.60 ± 0.10
	B	0.50 ± 0.10
	C	0.40 ± 0.10

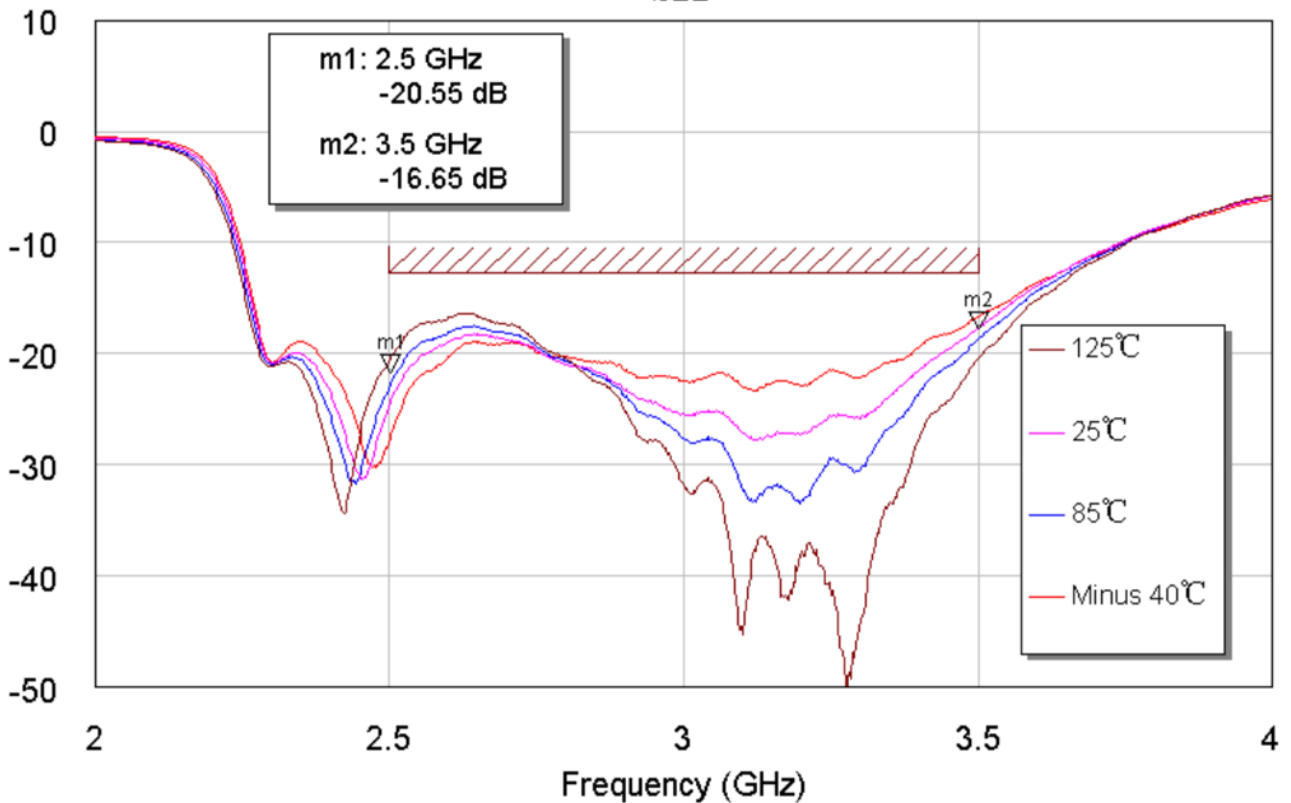
Typical Electrical Characteristics (T=25°C)



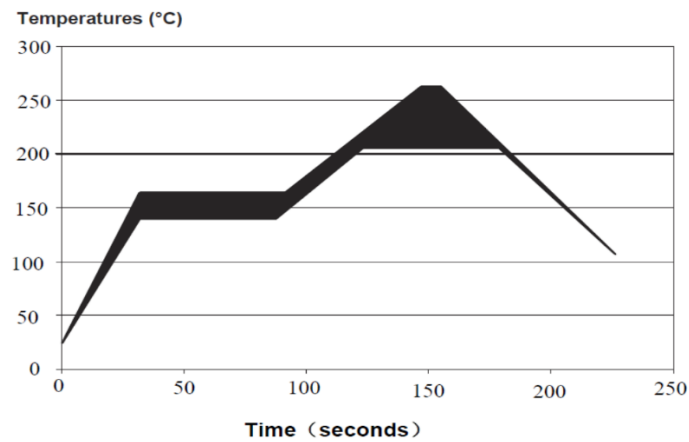
S11



S22



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.